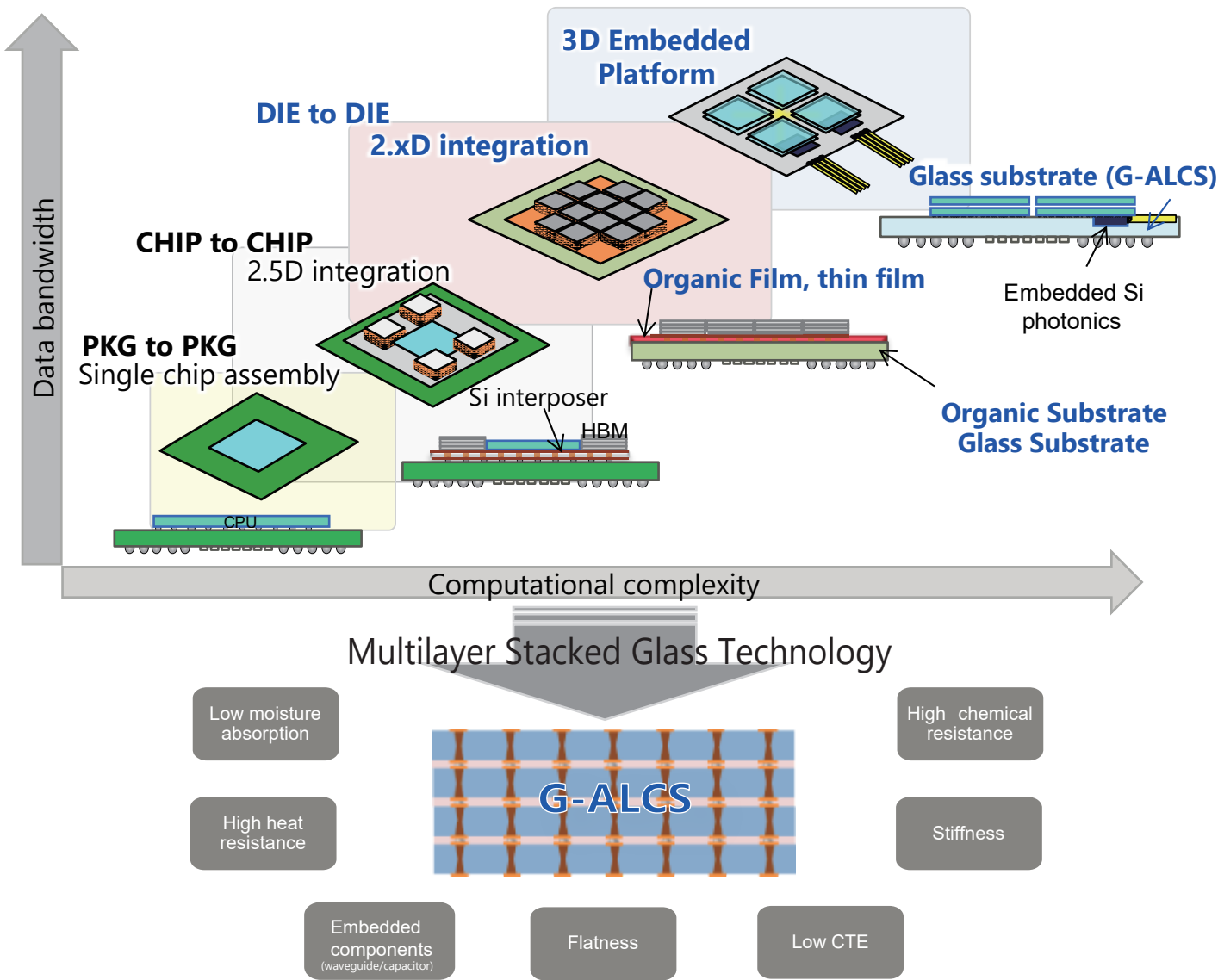


FICT Inorganic Substrate Technologies:
G-ALCS (Glass All Layer Z-Connection Structure)

High density inorganic substrate : Multi glass core layers with conductive paste for customer’s specific needs for higher reliability

Next generation substrate technology for AI/HPC application



	CTE (ppm/°C)	Glass transition point	Young modulus	Roughness (μm)
Glass substrate	3-4 (same as Si)	>600°C	70GPa	<0.05
Organic substrate	10-17	150-200°C	5-10GPa	0.1-1.0

